

### ● General Description

The AGM028N08A combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

This device is ideal for load switch and battery protection applications.

### ● Features

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

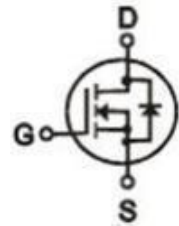
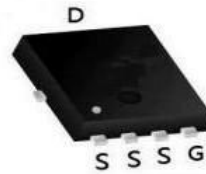
### ● Application

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

### Product Summary

BVDSS	RDSON	ID
85V	2.8mΩ	170A

### PDFN5\*6 Pin Configuration



### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM028N08A	AGM028N08A	PDFN5*6	----	----	3000

**Table 1. Absolute Maximum Ratings (TA=25°C)**

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	85	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) <b>(Note 1)</b>	170	A
	Drain Current-Continuous(Tc=100°C)	108	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed <b>(Note 2)</b>	680	A
PD	Maximum Power Dissipation(Tc=25°C)	167	w
	Maximum Power Dissipation(Tc=100°C)	67	w
EAS	Avalanche energy <b>(Note 3)</b>	530	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	50	°C/W
RθJC	Thermal Resistance Junction-Case <sup>1</sup>	---	0.75	°C/W

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

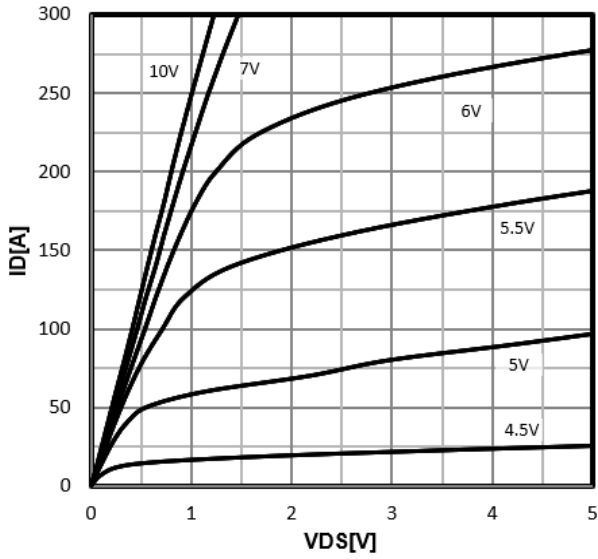
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	85	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=68V,VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	2.0	3.0	4.0	V
gFS	Forward Transconductance	VDS=10V,ID=15A	--	10	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=15A	--	2.8	3.5	mΩ
		VGS=4.5V, ID=20A	--	--	--	mΩ
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=50V,VGS=0V, F=1MHZ	--	3100	--	pF
Coss	Output Capacitance		--	1240	--	pF
Crss	Reverse Transfer Capacitance		--	63	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	1.55	--	Ω
<b>Switching Times</b>						
td(on)	Turn-on Delay Time	VGS=10V,VDS=50V, ID=30A,RGEN=3Ω	--	13.2	--	nS
tr	Turn-on Rise Time		--	17.8	--	nS
td(off)	Turn-Off Delay Time		--	55.2	--	nS
tf	Turn-Off Fall Time		--	27.9	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=50V, ID=30A	--	59.5	--	nC
Qgs	Gate-Source Charge		--	13.5	--	nC
Qgd	Gate-Drain Charge		--	19.8	--	nC
<b>Source-Drain Diode Characteristics</b>						
ISD	Source-Drain Current(Body Diode)		--	--	170	A
VSD	Forward on Voltage	VGS=0V,IS=20A	--	--	1.0	V
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/μs ,	--	56	--	ns
Qrr	Reverse Recovery Charge	TJ=25°C	--	79	--	nc

Notes 1.The maximum current rating is package limited.

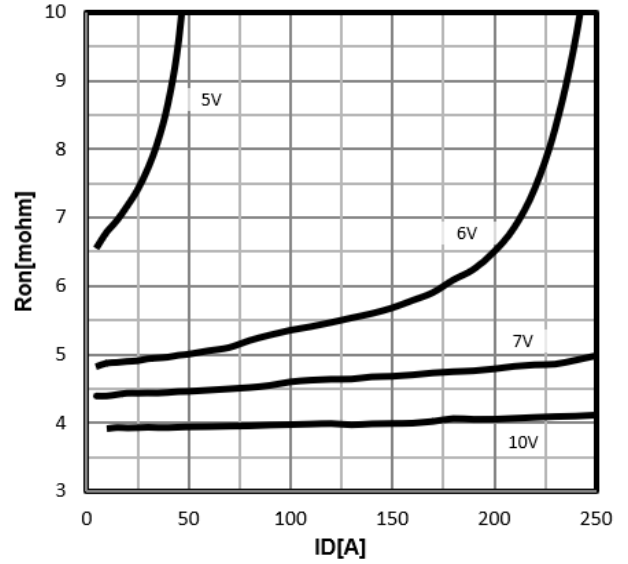
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C

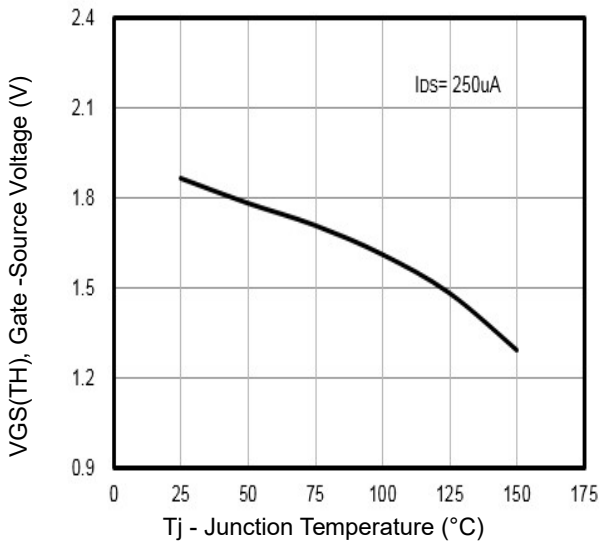
**Typ. output characteristics**  
 $I_D = f(V_{DS})$



**Typ. drain-source on resistance**  
 $R_{DS(on)} = f(I_D)$

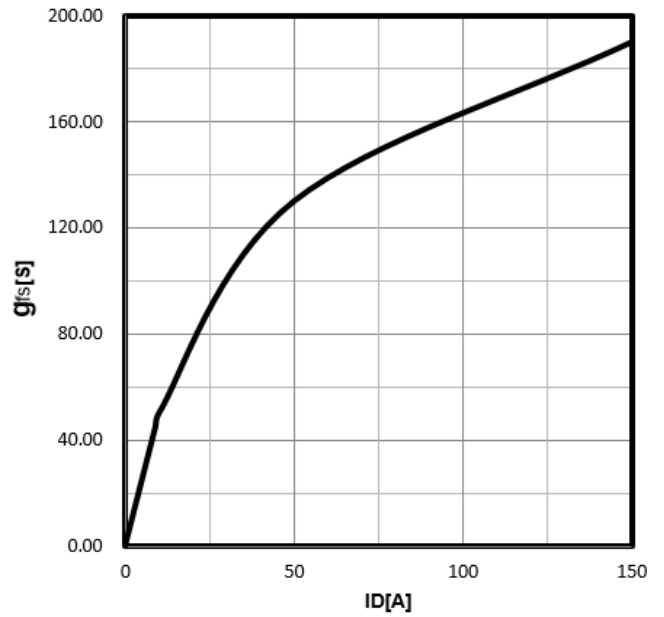


**Typ. transfer characteristics**  
 $I_D = f(V_{GS})$



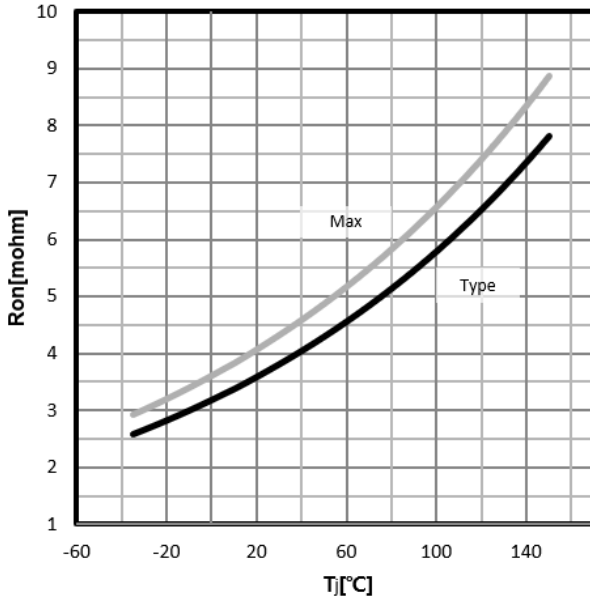
$V_{GS(TH)}$  Gate -Source Voltage Vs.  $T_j$

**Typ. forward transconductance**  
 $g_{fs} = f(I_D)$

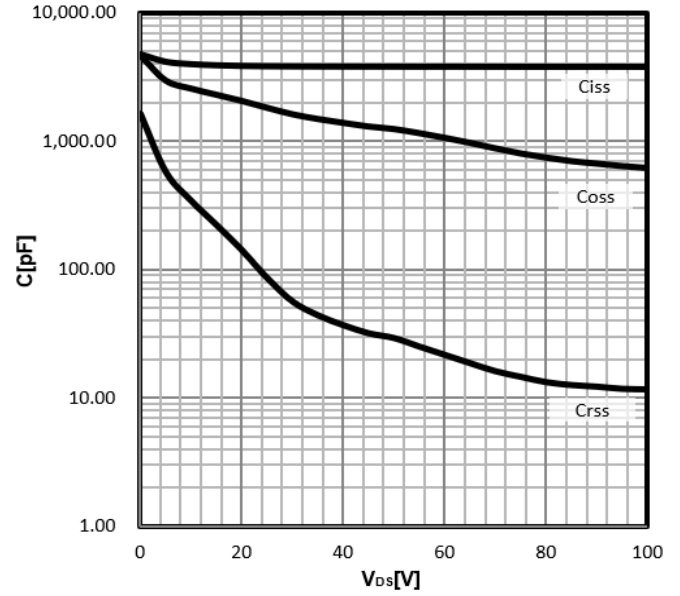


**Drain-source on-state resistance**

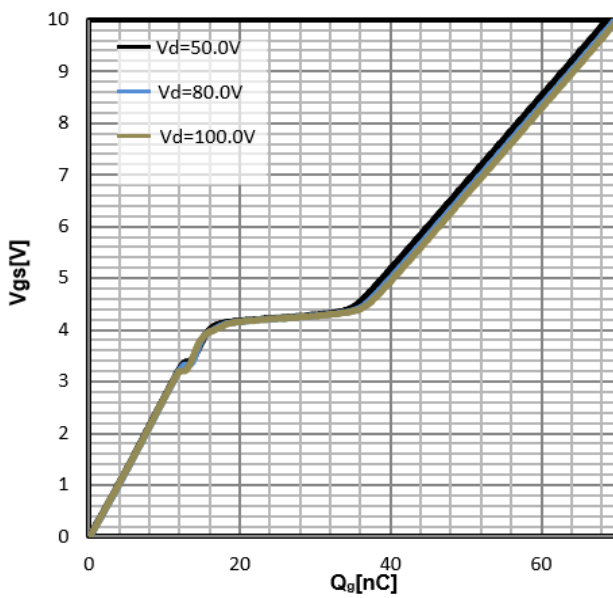
$$R_{DS(on)} = f(T_j); I_D = 56A; V_{GS} = 10V$$


**Typ. capacitances**

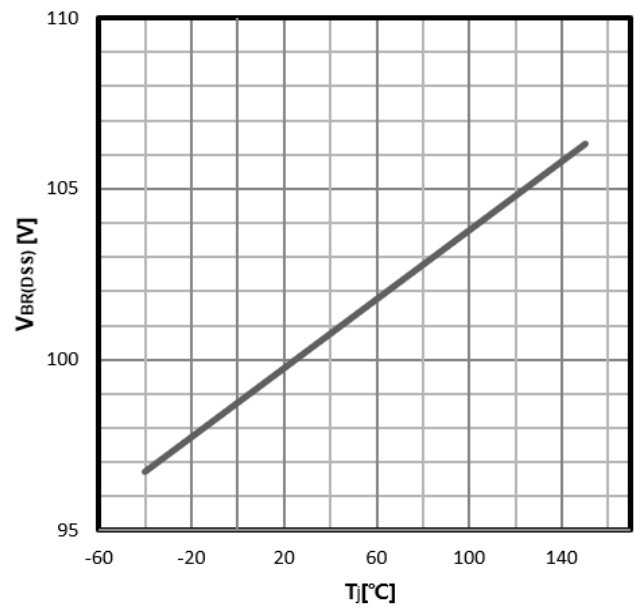
$$C = f(V_{DS}); V_{GS} = 0V; f = 1MHz$$


**Typ. gate charge**

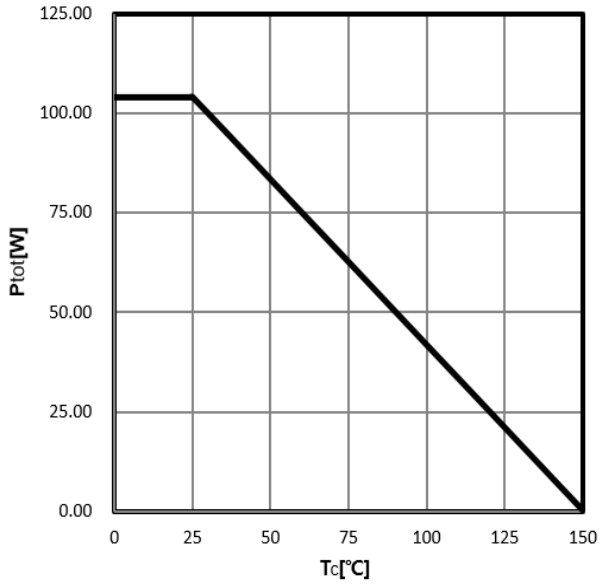
$$V_{GS} = f(Q_{gate}); I_D = 20A$$


**Drain-source breakdown voltage**

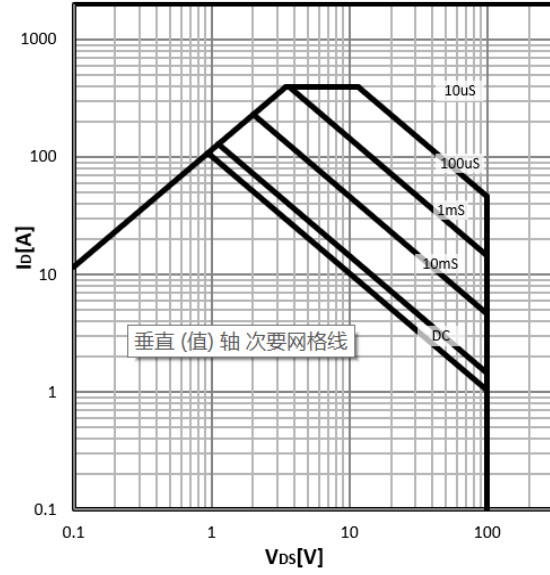
$$V_{BR(DSS)} = f(T_j); I_D = 250\mu A$$



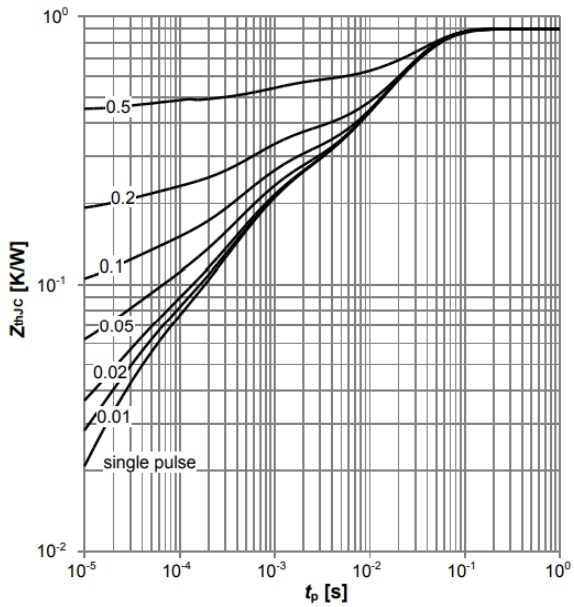
**Power Dissipation**  
 $P_{tot}=f(T_c)$

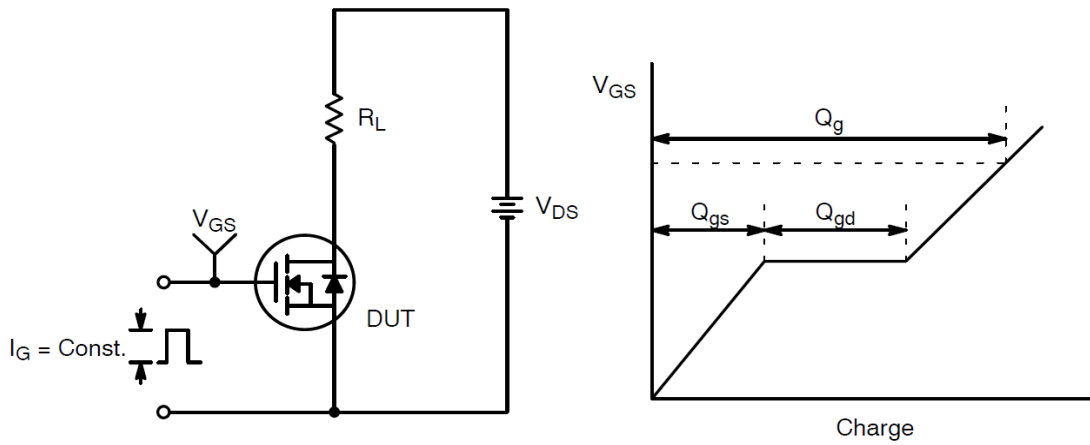
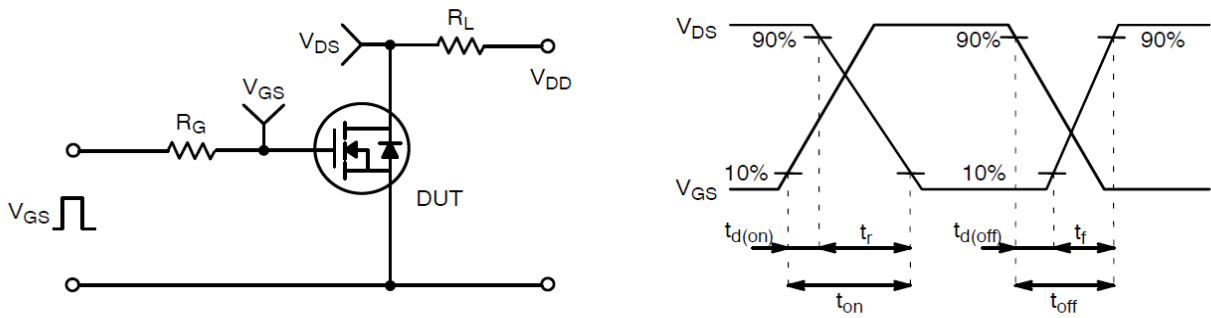
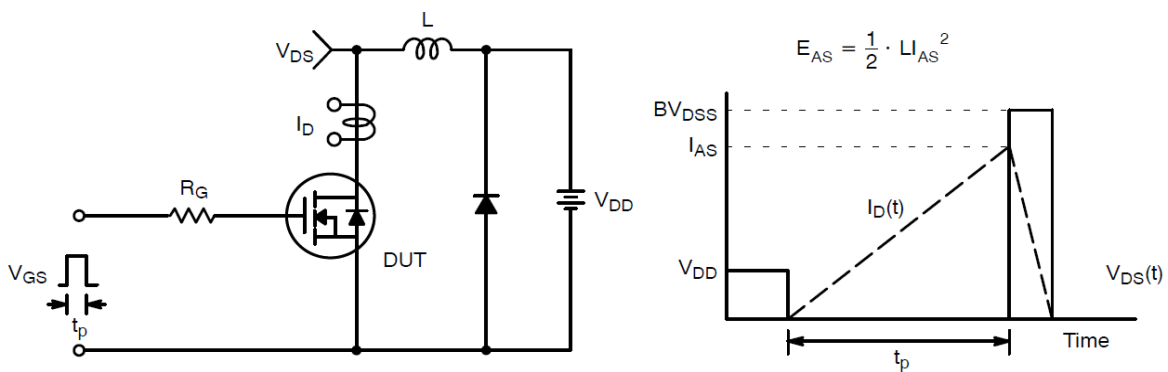


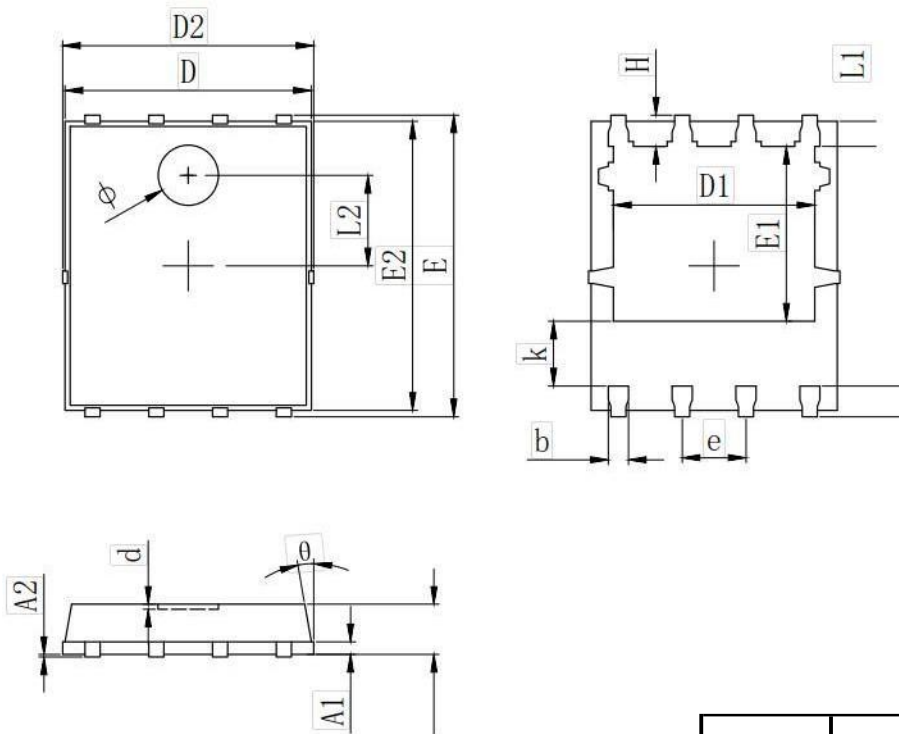
**Safe operating area**  
 $I_D=f(V_{DS})$



**Max. transient thermal impedance**  
 $Z_{thJC}=f(t_p)$



**Test Circuit and Waveform:**

**Gate Charge Test Circuit & Waveform**

**Resistive Switching Test Circuit & Waveforms**

**Unclamped Inductive Switching Test Circuit & Waveforms**

**•Dimensions (DFN5×6)**


SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
$\theta$	8°	10°	12°
$\phi$	1.100	1.200	1.300
d			0.100


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